

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-16. (canceled)

17. (currently amended) An electronic device comprising:

a wiring substrate including an insulating resin layer having a first major surface and a second major surface and a first wiring layer disposed on said insulating resin layer on the second major surface side;

a second wiring layer formed on the first major surface of said insulating resin layer;

a chip part including a projection electrode on a bottom surface and mounted on said wiring substrate; ~~and~~

wherein said insulating resin layer holds said chip part such that a bottom and at least a part of side surfaces of said chip part are in contact with said insulating resin layer, and a top surface of said chip part is exposed on said insulating resin layer on the first major surface side, and wherein the projection electrode of the chip part includes a sharp tip that is connected with said first wiring layer, and

wherein said chip part protrudes from the first major surface of said insulating resin layer.

18. (canceled)

19. (previously presented) The electronic device according to Claim 17, wherein a ground pattern is formed in said second wiring layer.

20. (previously presented) The electronic device according to Claim 17, further comprising a plurality of insulating resin layers for holding the chip part.

21. (previously presented) The electronic device according to Claim 20, wherein the insulating resin layers for holding the chip part are laminated such that the first major surfaces are faced in the same direction.

22. (previously presented) The electronic device according to Claim 17, wherein said insulating resin layers for holding said chip part are arranged on both surfaces of said wiring substrate.

23. (currently amended) An electronic device comprising:

a wiring substrate including a plurality of insulating resin layers that are laminated and have first major surfaces and second major surfaces and a first wiring layer disposed on said insulating resin layer on the second major surface side from a lowermost layer to an innermost layer in said resin insulating layers;

a second wiring layer formed on the first major surface of said insulating resin layer;

a chip part including a projection electrode on a bottom surface and mounted on said wiring substrate; ~~and~~

wherein said insulating resin layer holds said chip part such that a bottom and side surfaces of said chip part are in contact with said insulating resin layer in an outmost layer, and a top surface of said chip part is exposed on said insulating resin layer on the second major surface side, and wherein the projection electrode of the chip part includes a sharp tip that is connected with said first wiring layer, and

wherein said chip part protrudes from the first major surface of said insulating resin layer.

24. (previously presented) The electronic device according to Claim 17, wherein said wiring substrate further comprises an insulating layer except for said insulating resin layer and further comprises a wiring layer except for said first wiring layer or first and second wiring layers.

25. (previously presented) The electronic device according to Claim 17, wherein a portion exposed from the insulating resin layer of the chip part that enters the insulating resin layer of the outmost layer in the wiring substrate, is covered by a coating resin.

26. (canceled)

27. (previously presented) The electronic device according to Claim 17, wherein the projection electrode of said chip part is a gold electrode formed by a wire bonding technique.

28. (previously presented) The electronic device according to Claim 17, wherein said insulating resin layer is made of thermoplastic resin or materials in which thermosetting resin is added to thermoplastic resin.

29-32. (canceled)

33. (previously presented) The electronic device according to Claim 23, wherein said wiring substrate further comprises an insulating layer except for said insulating resin layer and further comprises a wiring layer except for said first wiring layer or first and second wiring layers.

34. (previously presented) The electronic device according to Claim 23, wherein a portion exposed from the insulating resin layer of the chip part that enters the insulating resin layer of the outmost layer in the wiring substrate, is covered by a coating resin.

35. (canceled)

36. (previously presented) The electronic device according to Claim 23, wherein the projection electrode of said chip part is a gold electrode formed by a wire bonding technique.

37. (previously presented) The electronic device according to Claim 23, wherein said insulating resin layer is made of thermoplastic resin or materials in which thermosetting resin is added to thermoplastic resin.

38. (previously presented) The electronic device according to claim 17, wherein the first major surface on which the second wiring layer is formed is arranged below the top surface of the chip part.

39. (previously presented) The electronic device according to claim 23, wherein the first major surface on which

the second wiring layer is formed is arranged below the top surface of the chip part.